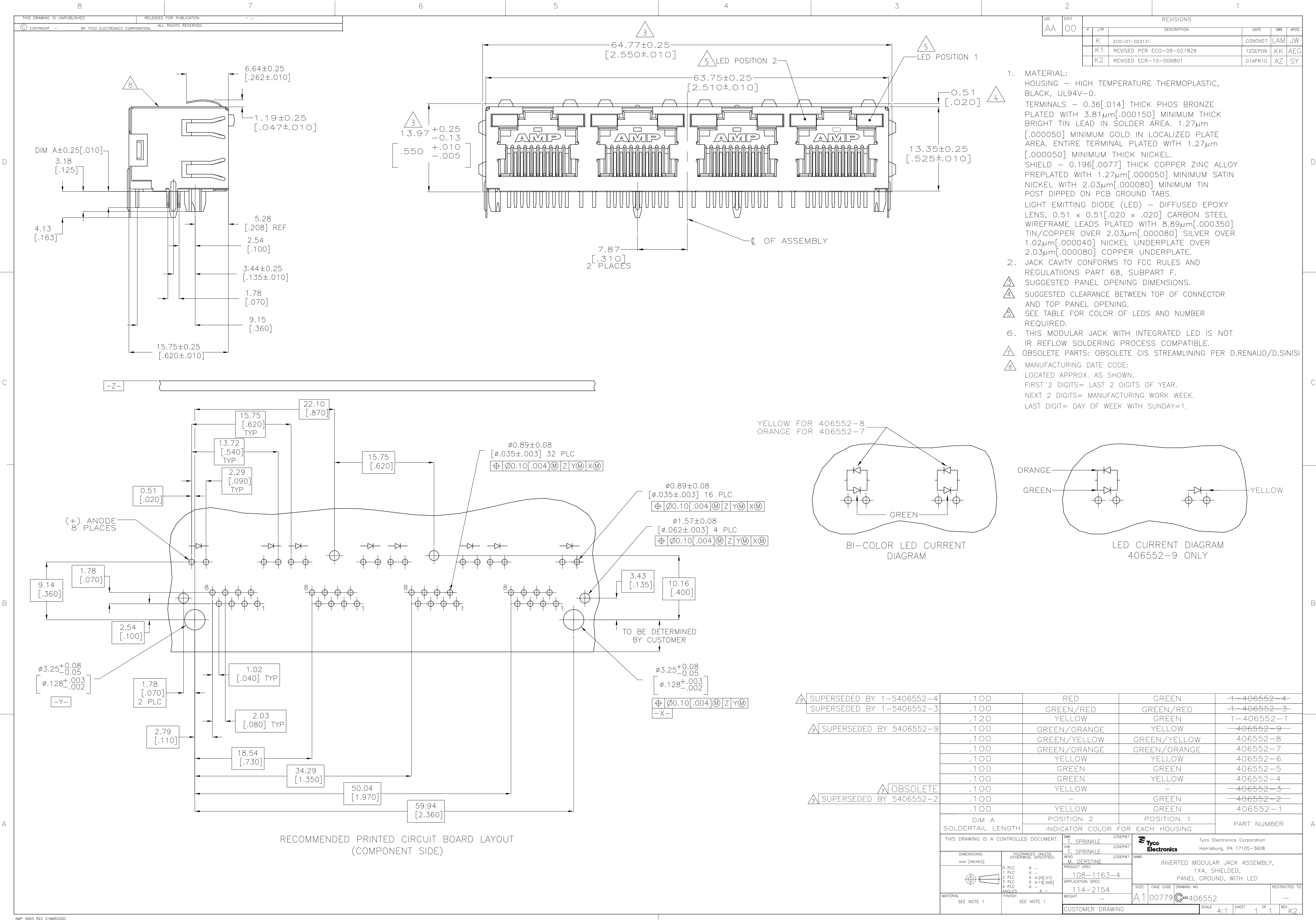
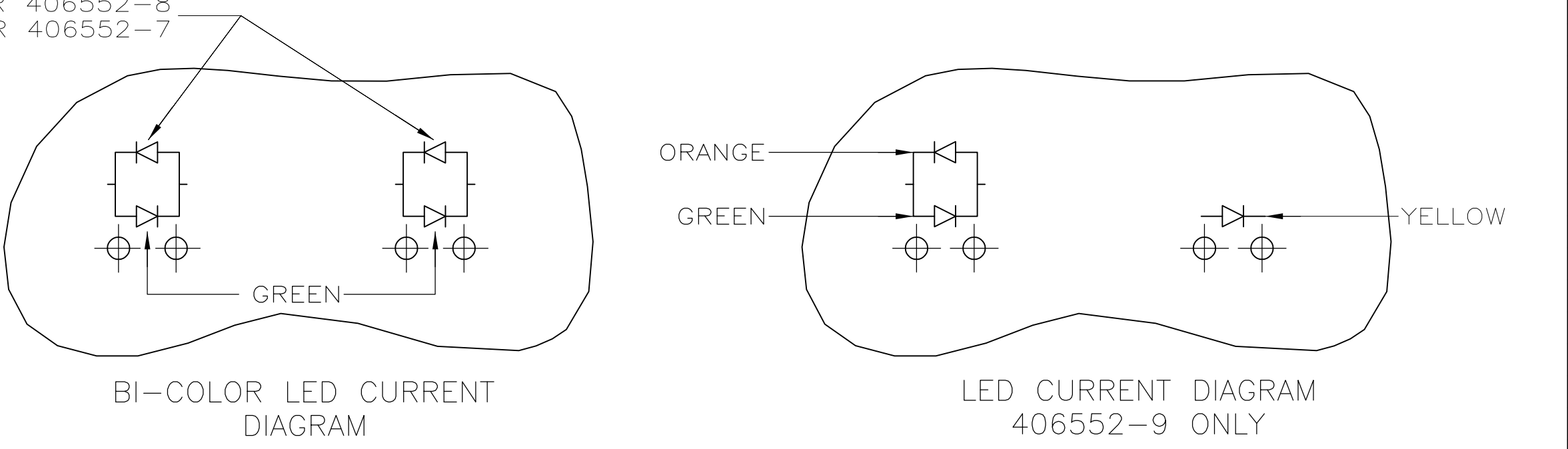


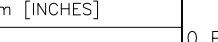


LOC		DIST		REVISIONS			
F	LTR	DESCRIPTION		DATE	DWN	APVD	
K		ECO-07-022131		03NOV07	LAM	JW	
K1		REVISED PER ECO-09-021826		12SEP09	KK	AEG	
K2		REVISED ECR-10-006801		01APR10	AZ	SY	

- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE.
JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
SUGGESTED PANEL OPENING DIMENSIONS.
SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
MANUFACTURING DATE CODE:
LOCATED APPROX. AS SHOWN.
FIRST 2 DIGITS= LAST 2 DIGITS OF YEAR.
NEXT 2 DIGITS= MANUFACTURING WORK WEEK.
LAST DIGIT= DAY OF WEEK WITH SUNDAY=1.



SUPERSEDED BY 1-5406552-4 SUPERSEDED BY 1-5406552-3 SUPERSEDED BY 5406552-9 OBSOLETE SUPERSEDED BY 5406552-2	.100	RED	GREEN	1-406552-4
	.100	GREEN/RED	GREEN/RED	1-406552-3
	.120	YELLOW	GREEN	1-406552-1
	.100	GREEN/ORANGE	YELLOW	406552-9
	.100	GREEN/YELLOW	GREEN/YELLOW	406552-8
	.100	GREEN/ORANGE	GREEN/ORANGE	406552-7
	.100	YELLOW	YELLOW	406552-6
	.100	GREEN	GREEN	406552-5
	.100	GREEN	YELLOW	406552-4
	.100	YELLOW	-	406552-3
DIM A	.100	-	GREEN	406552-2
	.100	YELLOW	GREEN	406552-1
SOLDER TAIL LENGTH		INDICATOR COLOR FOR EACH HOUSING		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. SPRINKLE 23SEP97	Tyco Electronics Corporation Harrisburg, PA 17105-3608		
DIMENSIONS: mm [INCHES]		CHK T. SPRINKLE 23SEP97	NAME		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD M. DERSTINE 23SEP97	PRODUCT SPEC		
		108-1163-4		INVERTED MODULAR JACK ASSEMBLY, 1X4, SHIELDED, PANEL GROUND, WITH LED	
		APPLICATION SPEC			
		114-2154			
		WEIGHT			
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1	A1 00779 ©=406552		RESTRICTED TO —
CUSTOMER DRAWING		SCALE 4:1		SHEET 1 OF 1	REV K2